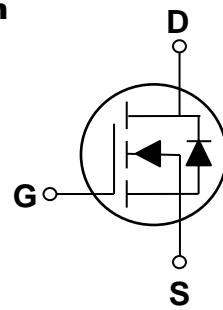
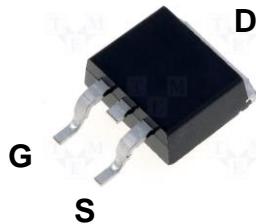


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

TO263 Pin Configuration



BVDSS	RDS(ON)	ID
200V	24mΩ	60A

Features

- 200V,60A, RDS(ON) =24mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- Networking
- Load Switch
- LED applications
- Quick Charger



Absolute Maximum Ratings T_c=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V _{Ds}	Drain-Source Voltage	200	V
V _{Gs}	Gate-Source Voltage	±20	V
I _D	Drain Current – Continuous (T _c =25°C) (Chip Limitation)	60	A
	Drain Current – Continuous (T _c =100°C) (Chip Limitation)	38	A
I _{DM}	Drain Current – Pulsed ¹	240	A
EAS	Single Pulse Avalanche Energy ²	280	mJ
I _{AS}	Single Pulse Avalanche Current ²	75	A
P _D	Power Dissipation (T _c =25°C)	208	W
	Power Dissipation – Derate above 25°C	1.66	W/°C
T _{STG}	Storage Temperature Range	-50 to 150	°C
T _J	Operating Junction Temperature Range	-50 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	0.6	°C/W

Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	200	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to $25\text{ }^{\circ}\text{C}$, $I_D=1\text{mA}$	---	0.23	---	$\text{V}/\text{ }^{\circ}\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=200\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	μA
		$V_{DS}=160\text{V}$, $V_{GS}=0\text{V}$, $T_J=125\text{ }^{\circ}\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$, $I_D=12\text{A}$	---	19	24	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	1.5	2.2	3	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-4	---	$\text{mV}/\text{ }^{\circ}\text{C}$
g_{fs}	Forward Transconductance	$V_{DS}=5\text{V}$, $I_D=10\text{A}$	---	35	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{3, 4}	$V_{DS}=160\text{V}$, $V_{GS}=10\text{V}$, $I_D=10\text{A}$	---	238	450	nC
Q_{gs}	Gate-Source Charge ^{3, 4}		---	62	140	
Q_{gd}	Gate-Drain Charge ^{3, 4}		---	58	150	
$T_{d(on)}$	Turn-On Delay Time ^{3, 4}	$V_{DD}=50\text{V}$, $V_{GS}=10\text{V}$, $R_G=6\Omega$ $I_D=1\text{A}$	---	55.2	100	ns
T_r	Rise Time ^{3, 4}		---	64.6	120	
$T_{d(off)}$	Turn-Off Delay Time ^{3, 4}		---	202	400	
T_f	Fall Time ^{3, 4}		---	88	160	
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	15325	22000	pF
C_{oss}	Output Capacitance		---	573	900	
C_{rss}	Reverse Transfer Capacitance		---	34	70	
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $F=1\text{MHz}$	---	1.8	3.6	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	60	A
I_{SM}	Pulsed Source Current		---	---	120	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=1\text{A}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=50\text{V}$, $V_{GS}=10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=75\text{A}$, $R_G=25\Omega$, Starting $T_J=25\text{ }^{\circ}\text{C}$.
3. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

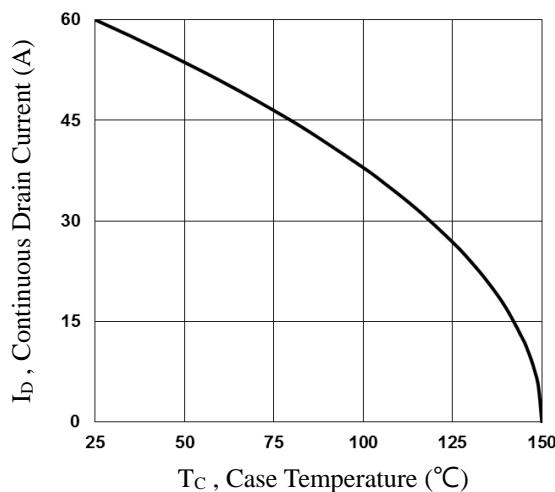


Fig.1 Continuous Drain Current vs. Tc

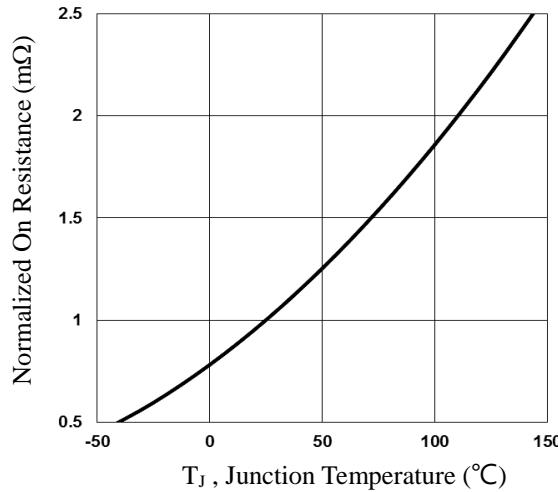


Fig.2 Normalized RDSON vs. Tj

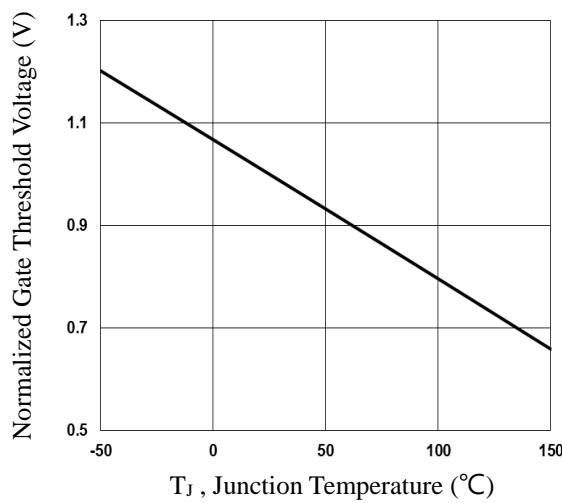


Fig.3 Normalized Vth vs. Tj

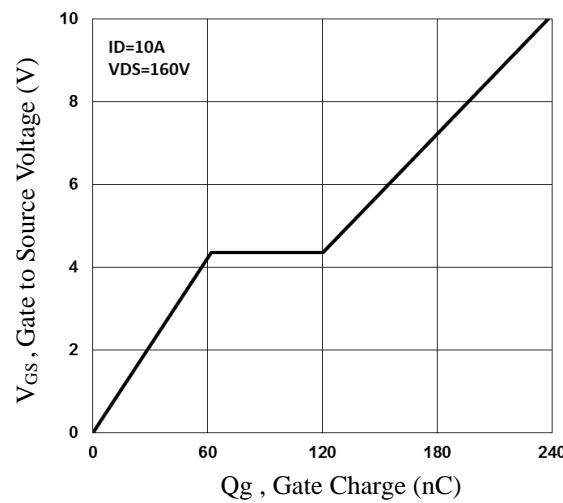


Fig.4 Gate Charge Characteristics

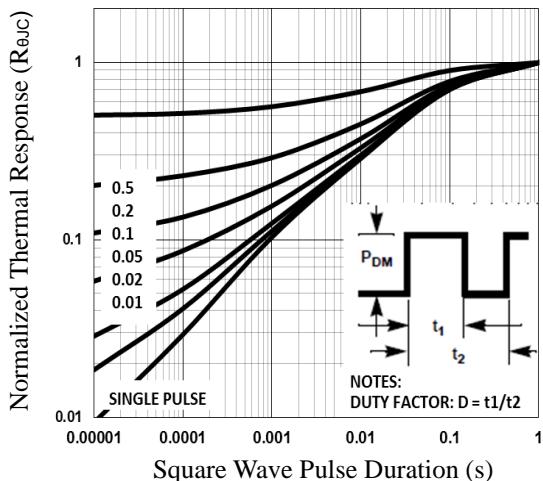


Fig.5 Normalized Transient Impedance

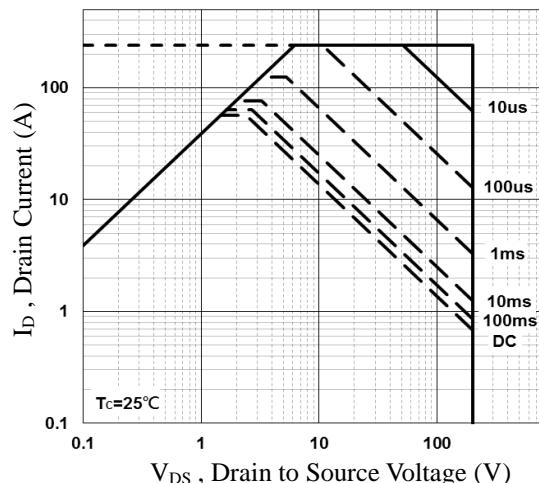


Fig.6 Maximum Safe Operation Area

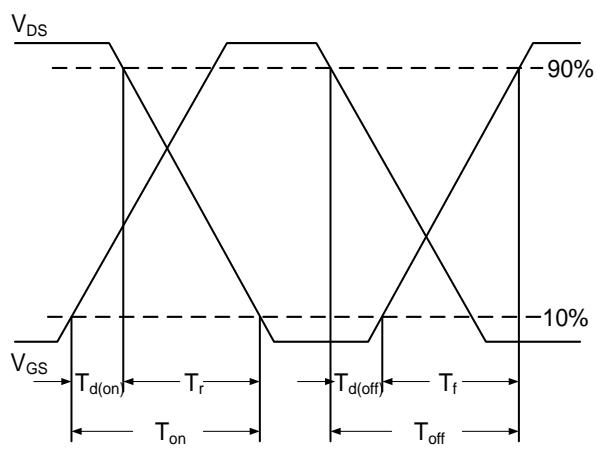


Fig.7 Switching Time Waveform

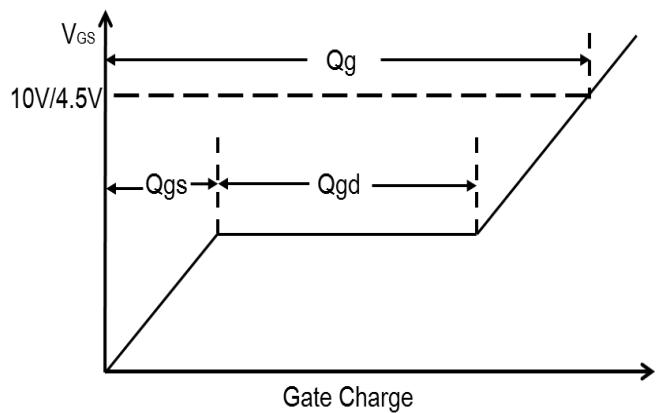


Fig.8 Gate Charge Waveform



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TECHNOLOGY

200V N-Channel MOSFETs

SPH50N20

TO263 PACKAGE INFORMATION

